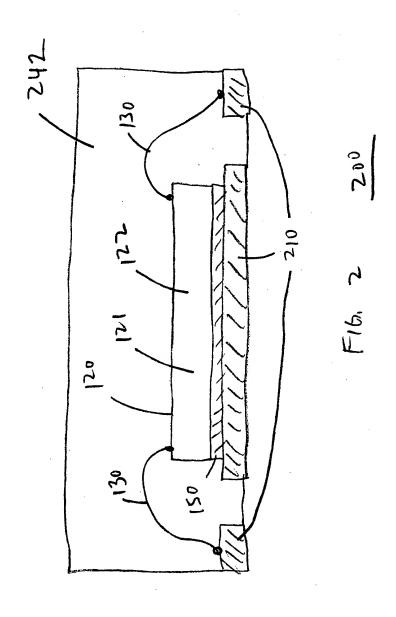


F16. 1 100

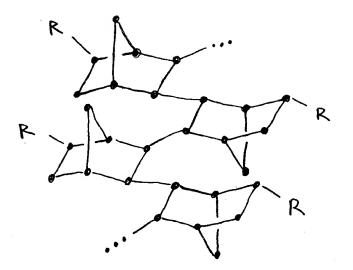


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F16. 3

3.00



F16. 4

400



F16. 5

500

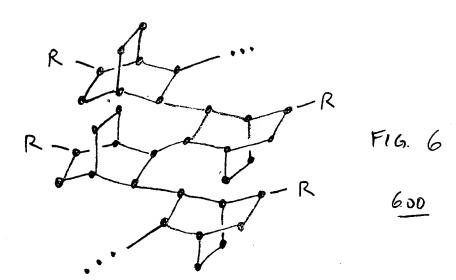


FIG. 7

<u>700</u>

710	Providing a semiconductor substrate
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720	Providing a lead frame
	<u> </u>
730	Mounting the semiconductor substrate over the lead frame
	\
740	Electrically coupling a device in the semiconductor substrate to the lead frame
	—
750	Mixing a catalyst with monomer of an optically transparent cycloaliphatic polymer to form a packaging material
	\
760	Filtering the packaging material
	<u> </u>
770	Applying the packaging material over the semiconductor substrate and the lead frame
	. \
780	Curing the packaging material